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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4/M0
Core Size	32-Bit Dual-Core
Speed	204MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, IrDA, Microwire, MMC/SD, SPI, SSI, SSP, UART/USART, USB, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, WDT
Number of I/O	83
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	136K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 8x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc43s37jbd144e

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P1_8	R7	H5	71	51	[2]	N; PU	I/O	**GPIO1[1] —** General purpose digital input/output pin.
							O	**U1_DTR —** Data Terminal Ready output for UART1.
							O	**CTOUT_12 —** SCT output 12. Match output 3 of timer 3.
							I/O	**EMC_D1 —** External memory data line 1.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**SD_VOLT0 —** SD/MMC bus voltage select output 0.
P1_9	T7	J5	73	52	[2]	N; PU	I/O	**GPIO1[2] —** General purpose digital input/output pin.
							O	**U1_RTS —** Request to Send output for UART1.
							O	**CTOUT_11 —** SCT output 11. Match output 3 of timer 2.
							I/O	**EMC_D2 —** External memory data line 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SD_DAT0 —** SD/MMC data bus line 0.
P1_10	R8	H6	75	53	[2]	N; PU	I/O	**GPIO1[3] —** General purpose digital input/output pin.
							I	**U1_RI —** Ring Indicator input for UART1.
							O	**CTOUT_14 —** SCT output 14. Match output 2 of timer 3.
							I/O	**EMC_D3 —** External memory data line 3.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SD_DAT1 —** SD/MMC data bus line 1.
P1_11	T9	J7	77	55	[2]	N; PU	I/O	**GPIO1[4] —** General purpose digital input/output pin.
							I	**U1_CTS —** Clear to Send input for UART1.
							O	**CTOUT_15 —** SCT output 15. Match output 3 of timer 3.
							I/O	**EMC_D4 —** External memory data line 4.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SD_DAT2 —** SD/MMC data bus line 2.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P1_20	M10	K10	100	70	[2]	N; PU	I/O	**GPIO0[15] —** General purpose digital input/output pin.
							I/O	**SSP1_SSEL —** Slave Select for SSP1.
							-	**R —** Function reserved.
							O	**ENET_TXD1 —** Ethernet transmit data 1 (RMII/MII interface).
							I	**T0_CAP2 —** Capture input 2 of timer 0.
							-	**R —** Function reserved.
							I/O	**SGPIO13 —** General purpose digital input/output pin.
							I/O	**EMC_D11 —** External memory data line 11.
P2_0	T16	G10	108	75	[2]	N; PU	I/O	**SGPIO4 —** General purpose digital input/output pin.
							O	**U0_TXD —** Transmitter output for USART0. See Table 4 for ISP mode.
							I/O	**EMC_A13 —** External memory address line 13.
							O	**USB0_PPWR —** VBUS drive signal (towards external charge pump or power management unit); indicates that VBUS must be driven (active HIGH). Add a pull-down resistor to disable the power switch at reset. This signal has opposite polarity compared to the USB_PPWR used on other NXP LPC parts.
							I/O	**GPIO5[0] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							I	**T3_CAP0 —** Capture input 0 of timer 3.
							O	**ENET_MDC —** Ethernet MIIM clock.
P2_1	N15	G7	116	81	[2]	N; PU	I/O	**SGPIO5 —** General purpose digital input/output pin.
							I	**U0_RXD —** Receiver input for USART0. See Table 4 for ISP mode.
							I/O	**EMC_A12 —** External memory address line 12.
							I	**USB0_PWR_FAULT —** Port power fault signal indicating overcurrent condition; this signal monitors over-current on the USB bus (external circuitry required to detect over-current condition).
							I/O	**GPIO5[1] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							I	**T3_CAP1 —** Capture input 1 of timer 3.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P2_13	C16	A10	156	108	[2]	N; PU	I/O	**GPIO1[13] —** General purpose digital input/output pin.
							I	**CTIN_4 —** SCT input 4. Capture input 2 of timer 1.
							-	**R —** Function reserved.
							I/O	**EMC_A4 —** External memory address line 4.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**U2_DIR —** RS-485/EIA-485 output enable/direction control for USART2.
P3_0	F13	A8	161	112	[2]	N; PU	I/O	**I2S0_RX_SCK —** I2S receive clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the *I²S-bus specification*.
							O	**I2S0_RX_MCLK —** I2S receive master clock.
							I/O	**I2S0_TX_SCK —** Transmit Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the I²S-bus specification.
							O	**I2S0_TX_MCLK —** I2S transmit master clock.
							I/O	**SSP0_SCK —** Serial clock for SSP0.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P3_1	G11	F7	163	114	[2]	N; PU	I/O	**I2S0_TX_WS —** Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the *I²S-bus specification*.
							I/O	**I2S0_RX_WS —** Receive Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the *I²S-bus specification*.
							I	**CAN0_RD —** CAN receiver input.
							O	**USB1_IND1 —** USB1 Port indicator LED control output 1.
							I/O	**GPIO5[8] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							O	**LCD_VD15 —** LCD data.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P6_0	M12	H7	105	73	[2]	N; PU	-	**R —** Function reserved.
							O	**I2S0_RX_MCLK —** I2S receive master clock.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**I2S0_RX_SCK —** Receive Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the *I²S-bus specification*.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_1	R15	G5	107	74	[2]	N; PU	I/O	**GPIO3[0] —** General purpose digital input/output pin.
							O	**$\overline{\text{EMC\_DYCS1}}$ —** SDRAM chip select 1.
							I/O	**U0_UCLK —** Serial clock input/output for USART0 in synchronous mode.
							I/O	**I2S0_RX_WS —** Receive Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the *I²S-bus specification*.
							-	**R —** Function reserved.
							I	**T2_CAP0 —** Capture input 2 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_2	L13	J9	111	78	[2]	N; PU	I/O	**GPIO3[1] —** General purpose digital input/output pin.
							O	**EMC_CKEOUT1 —** SDRAM clock enable 1.
							I/O	**U0_DIR —** RS-485/EIA-485 output enable/direction control for USART0.
							I/O	**I2S0_RX_SDA —** I2S Receive data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the *I²S-bus specification*.
							-	**R —** Function reserved.
							I	**T2_CAP1 —** Capture input 1 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P8_6	K3	-	43	-	[2]	N; PU	I/O	**GPIO4[6] —** General purpose digital input/output pin.
							I	**USB1_ULPI_NXT —** ULPI link NXT signal. Data flow control signal from the PHY.
							-	**R —** Function reserved.
							O	**LCD_VD5 —** LCD data.
							O	**LCD_LP —** Line synchronization pulse (STN). Horizontal synchronization pulse (TFT).
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**T0_CAP2 —** Capture input 2 of timer 0.
P8_7	K1	-	45	-	[2]	N; PU	I/O	**GPIO4[7] —** General purpose digital input/output pin.
							O	**USB1_ULPI_STP —** ULPI link STP signal. Asserted to end or interrupt transfers to the PHY.
							-	**R —** Function reserved.
							O	**LCD_VD4 —** LCD data.
							O	**LCD_PWR —** LCD panel power enable.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**T0_CAP3 —** Capture input 3 of timer 0.
P8_8	L1	-	49	-	[2]	N; PU	-	**R —** Function reserved.
							I	**USB1_ULPI_CLK —** ULPI link CLK signal. 60 MHz clock generated by the PHY.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**CGU_OUT0 —** CGU spare clock output 0.
							O	**I2S1_TX_MCLK —** I2S1 transmit master clock.
P9_0	T1	-	59	-	[2]	N; PU	I/O	**GPIO4[12] —** General purpose digital input/output pin.
							O	**$\overline{\text{MCABORT}}$ —** Motor control PWM, LOW-active fast abort.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**ENET_CRS —** Ethernet Carrier Sense (MII interface).
							I/O	**SGPIO0 —** General purpose digital input/output pin.
							I/O	**SSP0_SSEL —** Slave Select for SSP0.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
PA_2	K15	-	136	-	[3]	N; PU	I/O	**GPIO4[9] —** General purpose digital input/output pin.
							I	**QEI_PHB —** Quadrature Encoder Interface PHB input.
							-	**R —** Function reserved.
							I	**U2_RXD —** Receiver input for USART2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PA_3	H11	-	147	-	[3]	N; PU	I/O	**GPIO4[10] —** General purpose digital input/output pin.
							I	**QEI_PHA —** Quadrature Encoder Interface PHA input.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PA_4	G13	-	151	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_9 —** SCT output 9. Match output 3 of timer 3.
							-	**R —** Function reserved.
							I/O	**EMC_A23 —** External memory address line 23.
							I/O	**GPIO5[19] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PB_0	B15	-	164	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_10 —** SCT output 10. Match output 3 of timer 3.
							O	**LCD_VD23 —** LCD data.
							-	**R —** Function reserved.
							I/O	**GPIO5[20] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
PD_15	T15	-	101	-	[2]	N; PU	-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**EMC_A17 —** External memory address line 17.
							-	**R —** Function reserved.
							I/O	**GPIO6[29] —** General purpose digital input/output pin.
							I	**SD_WP —** SD/MMC card write protect input.
							O	**CTOUT_8 —** SCT output 8. Match output 0 of timer 2.
							-	**R —** Function reserved.
PD_16	R14	-	104	-	[2]	N; PU	-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**EMC_A16 —** External memory address line 16.
							-	**R —** Function reserved.
							I/O	**GPIO6[30] —** General purpose digital input/output pin.
							O	**SD_VOLT2 —** SD/MMC bus voltage select output 2.
							O	**CTOUT_12 —** SCT output 12. Match output 3 of timer 3.
							-	**R —** Function reserved.
PE_0	P14	-	106	-	[2]	N; PU	-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**EMC_A18 —** External memory address line 18.
							I/O	**GPIO7[0] —** General purpose digital input/output pin.
							O	**CAN1_TD —** CAN1 transmitter output.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PE_1	N14	-	112	-	[2]	N; PU	-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**EMC_A19 —** External memory address line 19.
							I/O	**GPIO7[1] —** General purpose digital input/output pin.
							I	**CAN1_RD —** CAN1 receiver input.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
PE_10	E14	-	154	-	[2]	N; PU	-	**R —** Function reserved.
							I	**CTIN_3 —** SCT input 3. Capture input 1 of timer 1.
							O	**U1_DTR —** Data Terminal Ready output for UART 1. Can also be configured to be an RS-485/EIA-485 output enable signal for UART 1.
							I/O	**EMC_D29 —** External memory data line 29.
							I/O	**GPIO7[10] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PE_11	D16	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_12 —** SCT output 12. Match output 3 of timer 3.
							O	**U1_TXD —** Transmitter output for UART 1.
							I/O	**EMC_D30 —** External memory data line 30.
							I/O	**GPIO7[11] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PE_12	D15	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_11 —** SCT output 11. Match output 3 of timer 2.
							I	**U1_RXD —** Receiver input for UART 1.
							I/O	**EMC_D31 —** External memory data line 31.
							I/O	**GPIO7[12] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PE_13	G14	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_14 —** SCT output 14. Match output 2 of timer 3.
							I/O	**I2C1_SDA —** I^2C1 data input/output (this pin does not use a specialized I2C pad).
							O	**EMC_DQMOUT3 —** Data mask 3 used with SDRAM and static devices.
							I/O	**GPIO7[13] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

7.6.1 Features

- ARM Cortex-M4 core:
  - Controls system exceptions and peripheral interrupts
  - Support for up to 53 vectored interrupts
  - Eight programmable interrupt priority levels with hardware priority level masking
  - Relocatable vector table
  - Non-Maskable Interrupt (NMI)
  - Software interrupt generation
- ARM Cortex-M0 core:
  - Support for up to 32 interrupts
  - Four programmable interrupt priority levels with hardware priority level masking

7.6.2 Interrupt sources

Each peripheral device has one interrupt line connected to the NVIC but may have several interrupt flags. Individual interrupt flags may also represent more than one interrupt source.

7.7 System Tick timer (SysTick)

The ARM Cortex-M4 includes a system tick timer (SYSTICK) that is intended to generate a dedicated SYSTICK exception at a 10 ms interval.

Remark: The SysTick is not included in the ARM Cortex-M0 core implementation.

7.8 Event router

The event router combines various internal signals, interrupts, and the external interrupt pins (WAKEUP[3:0]) to create an interrupt in the NVIC, if enabled. In addition, the event router creates a wake-up signal to the ARM core and the CCU for waking up from Sleep, Deep-sleep, Power-down, and Deep power-down modes. Individual events can be configured as edge or level sensitive and can be enabled or disabled in the event router. The event router can be battery powered.

The following events if enabled in the event router can create a wake-up signal from sleep, deep-sleep, power-down, and deep power-down modes and/or create an interrupt:

- External pins WAKEUP0/1/2/3 and $\overline{\text{RESET}}$
- Alarm timer, RTC (32 kHz oscillator running)

The following events if enabled in the event router can create a wake-up signal from sleep mode only and/or create an interrupt:

- WWDT, BOD interrupts
- C_CAN0/1 and QEI interrupts
- Ethernet, USB0, USB1 signals
- Selected outputs of combined timers (SCT and timer0/1/3)

Features

- Supports three digital event inputs in the VBAT power domain.
- An event is defined as a level change at the digital event inputs.
- For each event channel, two timestamps mark the first and the last occurrence of an event. Each channel also has a dedicated counter tracking the total number of events. Timestamp values are taken from the RTC.
- Runs in VBAT power domain, independent of system power supply. The event/recorder/monitor can therefore operate in Deep power-down mode.
- Low power consumption.
- Interrupt available if system is running.
- A qualified event can be used as a wake-up trigger.
- State of event interrupts accessible by software through GPIO.

7.22.2 Alarm timer

The alarm timer is a 16-bit timer and counts down at 1 kHz from a preset value generating alarms in intervals of up to 1 min. The counter triggers a status bit when it reaches 0x00 and asserts an interrupt if enabled.

The alarm timer is part of the RTC power domain and can be battery powered.

7.23 System control

7.23.1 Configuration registers (CREG)

The following settings are controlled in the configuration register block:

- BOD trip settings
- Oscillator output
- DMA-to-peripheral muxing
- Ethernet mode
- Memory mapping
- Timer/USART inputs
- Enabling the USB controllers

In addition, the CREG block contains the part identification and part configuration information.

7.23.2 System Control Unit (SCU)

The system control unit determines the function and electrical mode of the digital pins. By default function 0 is selected for all pins with pull-up enabled. For pins that support a digital and analog function, the ADC function select registers in the SCU enable the analog function.

A separate set of analog I/Os for the ADCs and the DAC as well as most USB pins are located on separate pads and are not controlled through the SCU.

In addition, the clock delay register for the SDRAM EMC_CLK pins and the registers that select the pin interrupts are located in the SCU.

Table 11. Static characteristics *…continued*
T_{amb} = −40 °C to +105 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
I_{BAT}	battery supply current	$V_{DD(REG)(3V3)}$ = 3.3 V; V_{BAT} = 3.6 V	[8]				
		deep-sleep mode		-	1.5	-	µA
		power-down mode	[8]	-	1.5	-	µA
		deep power-down mode	[8]	-	1.5	-	µA
I_{BAT}	battery supply current	Deep power-down mode; RTC running; $V_{DD(REG)(3V3)}$ floating; V_{BAT} = 3.3 V		-	3.0	-	µA
		$V_{DD(REG)(3V3)}$ = V_{BAT} = 3.3 V		-	1.5	-	µA
$I_{DD(IO)}$	I/O supply current	deep sleep mode		-	< 0.1	-	µA
		power-down mode		-	< 0.1	-	µA
		deep power-down mode		-	< 0.1	-	µA
I_{DDA}	Analog supply current	on pin VDDA;	[10]	-	0.4	-	
		deep sleep mode					µA
		power-down mode	[10]	-	0.4	-	µA
		deep power-down mode	[10]	-	0.007	-	µA
$\overline{\text{RESET}}$ pin							
V_{IH}	HIGH-level input voltage		[9]	0.8 × (V_{ps} − 0.35)	-	5.5	V
V_{IL}	LOW-level input voltage		[9]	−0.5	-	0.3 × (V_{ps} − 0.1)	V
V_{hys}	hysteresis voltage		[9]	0.05 × (V_{ps} − 0.35)	-	-	V
Standard I/O pins - normal drive strength							
C_I	input capacitance			-	-	2	pF
I_{LL}	LOW-level leakage current	V_I = 0 V; on-chip pull-up resistor disabled		-	3	-	nA
I_{LH}	HIGH-level leakage current	V_I = $V_{DD(IO)}$; on-chip pull-down resistor disabled		-	3	-	nA
		V_I = 5 V; T_{amb} = 25 °C		-	0.5	-	nA
		V_I = 5 V; T_{amb} = 105 °C		-	40	-	nA
I_{OZ}	OFF-state output current	V_O = 0 V to $V_{DD(IO)}$; on-chip pull-up/down resistors disabled; absolute value		-	3	-	nA
V_I	input voltage	pin configured to provide a digital function;		0	-	5.5	V
		$V_{DD(IO)} \geq$ 2.4 V					
		$V_{DD(IO)}$ = 0 V		0	-	3.6	V
V_O	output voltage	output active		0	-	$V_{DD(IO)}$	V

Table 12. Peripheral power consumption

Peripheral	Branch clock	$I_{DD(REG)(3V3)}$ in mA	
		Branch clock frequency = 48 MHz	Branch clock frequency = 96 MHz
GPIO	CLK_M4_GPIO	0.72	1.43
LCD	CLK_M4_LCD	0.91	1.82
ETHERNET	CLK_M4_ETHERNET	1.06	2.15
UART0	CLK_M4_UART0, CLK_APB0_UART0	0.24	0.43
UART1	CLK_M4_UART1, CLK_APB0_UART1	0.24	0.43
UART2	CLK_M4_UART2, CLK_APB2_UART2	0.26	0.5
UART3	CLK_M4_USART3, CLK_APB2_UART3	0.27	0.45
TIMER0	CLK_M4_TIMER0	0.08	0.15
TIMER1	CLK_M4_TIMER1	0.09	0.15
TIMER2	CLK_M4_TIMER2	0.1	0.19
TIMER3	CLK_M4_TIMER3	0.08	0.16
SDIO	CLK_M4_SDIO, CLK_SDIO	0.66	1.17
SCT	CLK_M4_SCT	0.66	1.3
SSP0	CLK_M4_SSP0, CLK_APB0_SSP0	0.13	0.23
SSP1	CLK_M4_SSP1, CLK_APB2_SSP1	0.14	0.27
DMA	CLK_M4_DMA	1.81	3.61
WWDT	CLK_M4_WWDT	0.03	0.09
QEI	CLK_M4_QEI	0.28	0.55
USB0	CLK_M4_USB0, CLK_USB0	1.9	3.9
USB1	CLK_M4_USB1, CLK_USB1	3.02	5.69
RITIMER	CLK_M4_RITIMER	0.05	0.1
EMC	CLK_M4_EMC, CLK_M4_EMC_DIV	3.94	7.95
SCU	CLK_M4_SCU	0.1	0.21
CREG	CLK_M4_CREG	0.35	0.7
Flash bank A	CLK_M4_FLASHA	1.47	2.97
Flash bank B	CLK_M4_FLASHB	1.4	2.84
SGPIO	CLK_PERIPH_SGPIO	0.1	0.17
SPI	CLK_SPI	0.07	0.11

10.4 BOD and band gap static characteristics

Table 13. BOD static characteristics[1]

T_{amb} = 25 °C; simulated values for nominal processing.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{th}	threshold voltage	interrupt level 0					
		assertion		-	2.25	-	V
		de-assertion		-	2.33	-	V
		interrupt level 1					
		assertion		-	2.35	-	V
		de-assertion		-	2.43	-	V
		interrupt level 2					
		assertion		-	2.95	-	V
		de-assertion		-	3.03	-	V
		interrupt level 3					
		assertion		-	3.05	-	V
		de-assertion		-	3.13	-	V
		reset level 0					
		assertion		-	1.9	-	V
		de-assertion		-	1.98	-	V
		reset level 1					
		assertion		-	2.0	-	V
		de-assertion		-	2.08	-	V
		reset level 2					
		assertion		-	2.1	-	V
		de-assertion		-	2.18	-	V
		reset level 3					
		assertion		-	2.2	-	V
		de-assertion		-	2.28	-	V

[1] Interrupt and reset levels are selected by writing to the BODLV1/2 bits in the control register CREGE0, see *the LPC43xx user manual*.

Table 14. Band gap characteristics

$V_{DDA(3V3)}$ over specified ranges; T_{amb} = −40 °C to +105 °C; unless otherwise specified

Symbol	Parameter		Min	Typ	Max	Unit
$V_{ref(bg)}$	band gap reference voltage	[1]	0.707	0.745	0.783	mV

[1] Based on characterization, not tested in production.

11.4 Crystal oscillator

Table 19. Dynamic characteristic: oscillator

T_{amb} = −40 °C to +105 °C; $V_{DD(IO)}$ over specified ranges; 2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V.[1]

Symbol	Parameter	Conditions		Min	Typ[2]	Max	Unit
Low-frequency mode (1-20 MHz)[5]							
$t_{jit(per)}$	period jitter time	5 MHz crystal	[3][4]	-	13.2	-	ps
		10 MHz crystal		-	6.6	-	ps
		15 MHz crystal		-	4.8	-	ps
High-frequency mode (20 - 25 MHz)[6]							
$t_{jit(per)}$	period jitter time	20 MHz crystal	[3][4]	-	4.3	-	ps
		25 MHz crystal		-	3.7	-	ps

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

[3] Indicates RMS period jitter.

[4] PLL-induced jitter is not included.

[5] Select HF = 0 in the XTAL_OSC_CTRL register.

[6] Select HF = 1 in the XTAL_OSC_CTRL register.

11.5 IRC oscillator

Table 20. Dynamic characteristic: IRC oscillator

2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
$f_{osc(RC)}$	internal RC oscillator frequency	-40 °C ≤ T_{amb} < 0 °C	12.0 - 3 %	12.0	12.0 + 3 %	MHz
		0 °C ≤ T_{amb} ≤ 85 °C	12.0 - 1.5 %	12.0	12.0 + 1.5 %	MHz
		85 °C < T_{amb} < 105 °C	12.0 - 3 %	12.0	12.0 + 3 %	MHz

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

11.6 RTC oscillator

See Section 13.3 for connecting the RTC oscillator to an external clock source.

Table 21. Dynamic characteristic: RTC oscillator

T_{amb} = −40 °C to +105 °C; 2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V or 2.4 V ≤ V_{BAT} ≤ 3.6 V[1]

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
f_i	input frequency	-		-	32.768	-	kHz
$I_{CC(osc)}$	oscillator supply current				280	800	nA

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

[9] A Fast-mode I^2C-bus device can be used in a Standard-mode I^2C-bus system but the requirement $t_{SU;DAT}$ = 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line $t_{r(max)} + t_{SU;DAT}$ = 1000 + 250 = 1250 ns (according to the Standard-mode I^2C-bus specification) before the SCL line is released. Also the acknowledge timing must meet this set-up time.

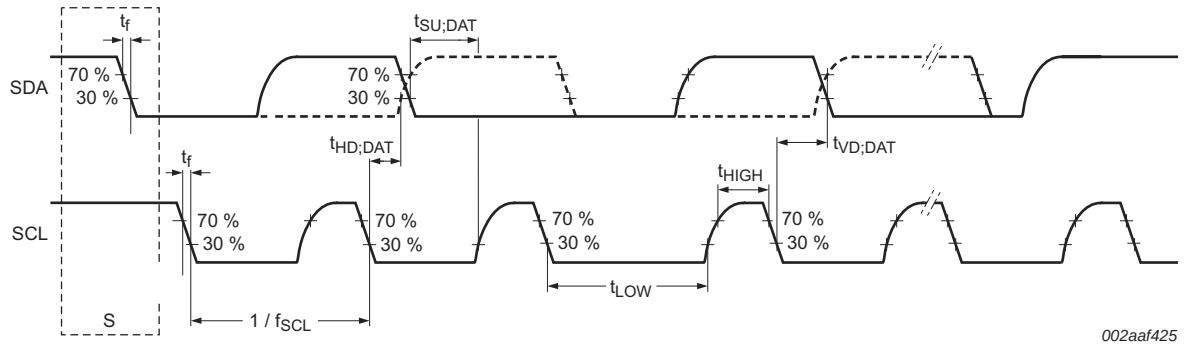

Fig 27. I^2C-bus pins clock timing

11.10 I^2S-bus interface

Table 25. Dynamic characteristics: I^2S-bus interface pins

T_{amb} = −40 °C to +105 °C; 2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V; C_L = 20 pF. Conditions and data refer to I2S0 and I2S1 pins. Simulated values.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
common to input and output							
t_r	rise time			-	4	-	ns
t_f	fall time			-	4	-	ns
t_{WH}	pulse width HIGH	on pins I2Sx_TX_SCK and I2Sx_RX_SCK		36	-	-	ns
t_{WL}	pulse width LOW	on pins I2Sx_TX_SCK and I2Sx_RX_SCK		36	-	-	ns
output							
$t_{v(Q)}$	data output valid time	on pin I2Sx_TX_SDA	[1]	-	4.4	-	ns
		on pin I2Sx_TX_WS		-	4.3	-	ns
input							
$t_{su(D)}$	data input set-up time	on pin I2Sx_RX_SDA	[1]	-	0	-	ns
		on pin I2Sx_RX_WS			0.20		ns
$t_{h(D)}$	data input hold time	on pin I2Sx_RX_SDA	[1]	-	3.7	-	ns
		on pin I2Sx_RX_WS		-	3.9	-	ns

[1] Clock to the I^2S-bus interface BASE_APB1_CLK = 150 MHz; peripheral clock to the I^2S-bus interface PCLK = BASE_APB1_CLK / 12. I^2S clock cycle time $T_{cy(clk)}$ = 79.2 ns, corresponds to the SCK signal in the *I^2S-bus specification*.

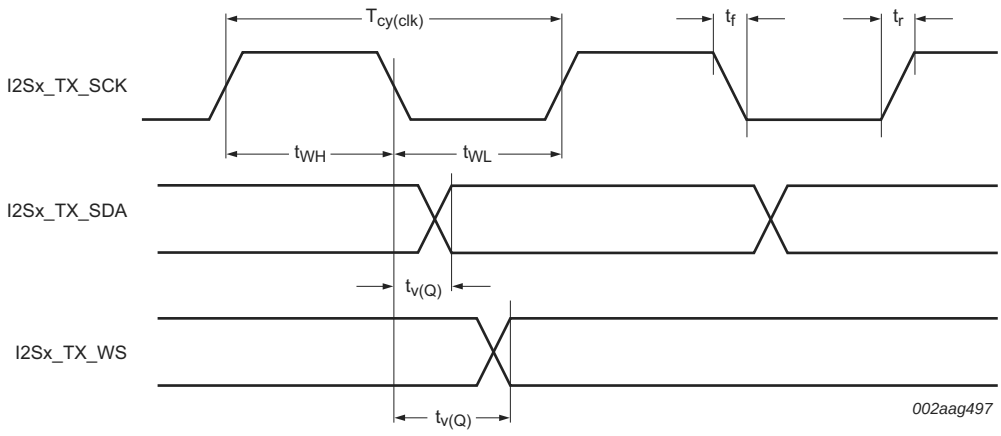

Fig 28. I²S-bus timing (transmit)

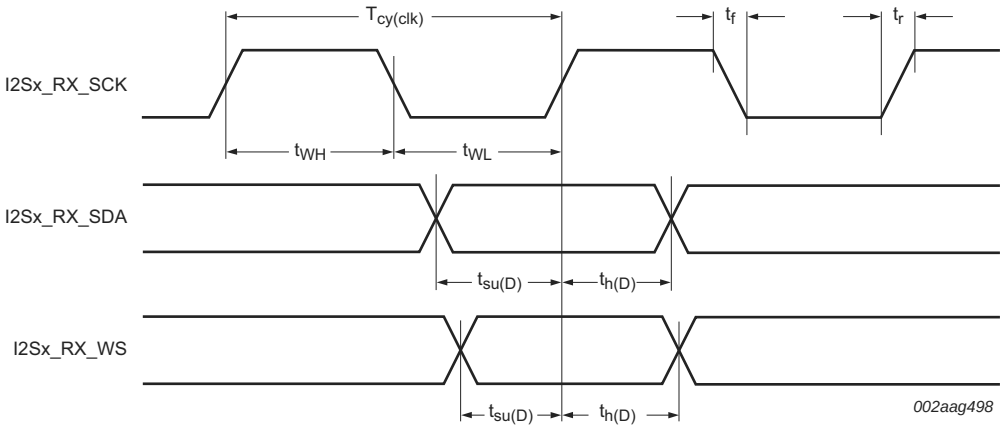

Fig 29. I²S-bus timing (receive)

11.11 USART interface

Table 26. Dynamic characteristics: USART interface

T_{amb} = −40 °C to 105 °C; 2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V; C_L = 20 pF. Simulated values.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$T_{cy(clk)}$	clock cycle time	on pins Ux_UCLK		-	0.1	-	µs
output							
$t_{v(Q)}$	data output valid time	on pin Ux_TXD		-	6.5	-	ns

Table 32. Dynamic characteristics: Static asynchronous external memory interface *…continued*

C_L = 22 pF for EMC_Dn C_L = 20 pF for all others; T_{amb} = −40 °C to +105 °C; 2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V; values guaranteed by design; the values in the table have been calculated with WAITTURN = 0x0 in STATICWAITTURN register. Timing parameters are given for single memory access cycles. In a normal read operation, the EMC changes the address while CS is asserted which results in multiple memory accesses.

Symbol	Parameter[1]	Conditions		Min	Typ	Max	Unit
$t_{BLSLBLSH}$	$\overline{BLS}$ LOW to $\overline{BLS}$ HIGH time	PB = 0	[2]	−0.9 + (WAITWR − WAITWEN + 1) × $T_{cy(clk)}$	-	−0.1 + (WAITWR − WAITWEN + 1) × $T_{cy(clk)}$	ns
$t_{BLSHEOW}$	$\overline{BLS}$ HIGH to end of write time	PB = 0	[2] [5]	−1.9 + $T_{cy(clk)}$	-	−0.5 + $T_{cy(clk)}$	ns
$t_{BLSHDNV}$	$\overline{BLS}$ HIGH to data invalid time	PB = 0	[2]	−2.5 + $T_{cy(clk)}$	-	1.4 + $T_{cy(clk)}$	ns
t_{CSHEOW}	$\overline{CS}$ HIGH to end of write time		[5]	−2.0	-	0	ns
$t_{BLSHDNV}$	$\overline{BLS}$ HIGH to data invalid time	PB = 1		−2.5	-	1.4	ns
t_{WEHANV}	WE HIGH to address invalid time	PB = 1		−0.9 + $T_{cy(clk)}$	-	2.4 + $T_{cy(clk)}$	ns

[1] Parameters specified for 40 % of $V_{DD(IO)}$ for rising edges and 60 % of $V_{DD(IO)}$ for falling edges.

[2] $T_{cy(clk)}$ = 1/CCLK (see LPC43xx User manual).

[3] End Of Read (EOR): longest of t_{CSHOEH}, t_{OEHANV}, $t_{CSHBLSH}$.

[4] Start Of Read (SOR): longest of t_{CSLAV}, t_{CSLOEL}, $t_{CSLBLSL}$.

[5] End Of Write (EOW): earliest of address not valid or $\overline{EMC\_BLSn}$ HIGH.

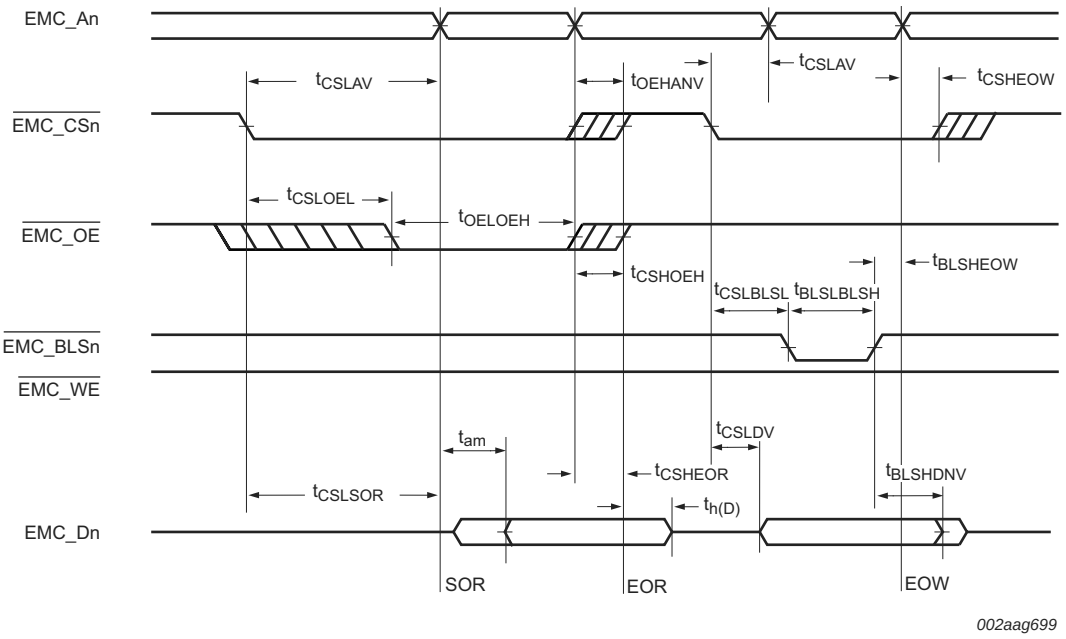

Fig 35. External static memory read/write access (PB = 0)

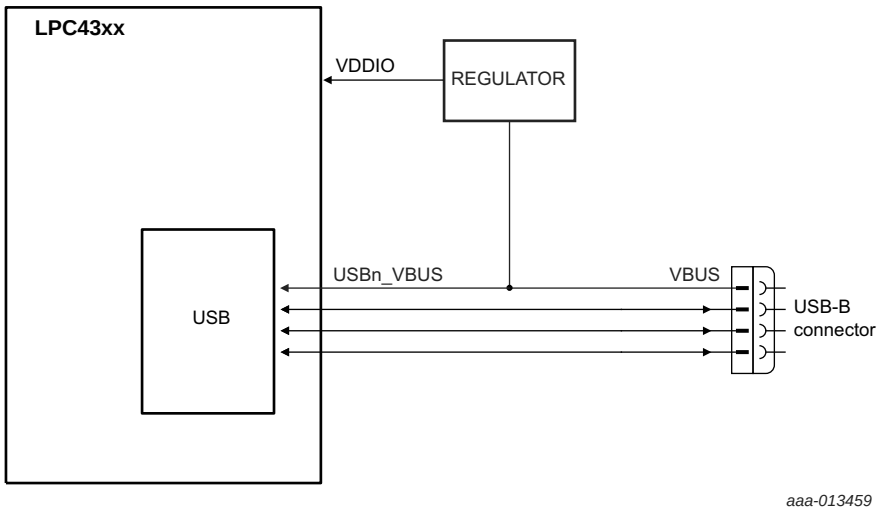

Fig 49. USB interface on a bus-powered device

Remark: If the VBUS function of the USB1 interface is not connected, configure the pin function for GPIO using the function control bits in the SYSCON block.

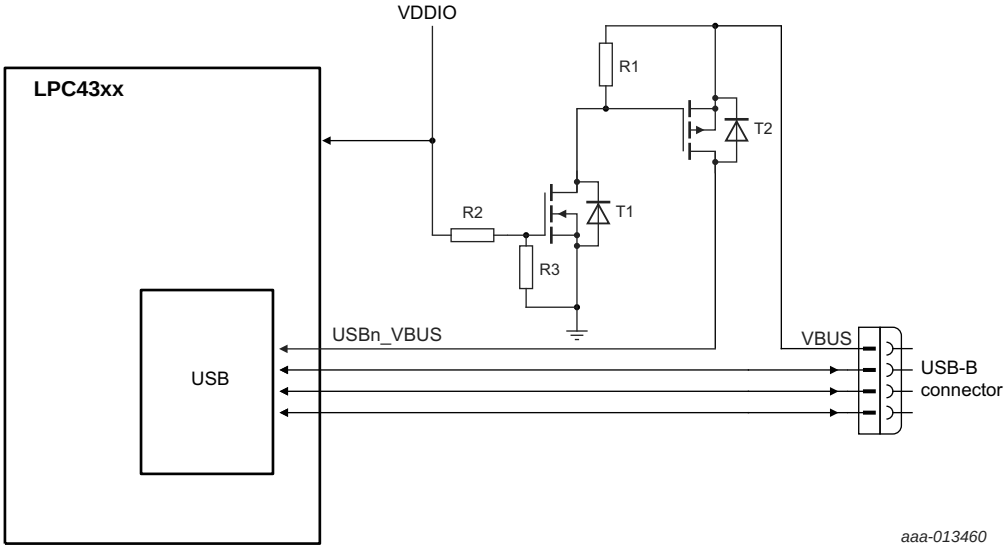

Fig 50. USB interface for USB operating in OTG mode

Remark: In OTG mode, it is important to be able to detect the VBUS level and to charge and discharge VBUS. This requires adding active devices that disconnect the link when VDDIO is not present.

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